

ME211: Engineering Materials

Course Objective...

Introduce fundamental concepts in Materials Science

You will learn about:

- material structure
- how structure dictates properties
- how processing can change structure

This course will help you to:

- use materials properly
- realize new design opportunities with materials



Chapter 1 - Introduction

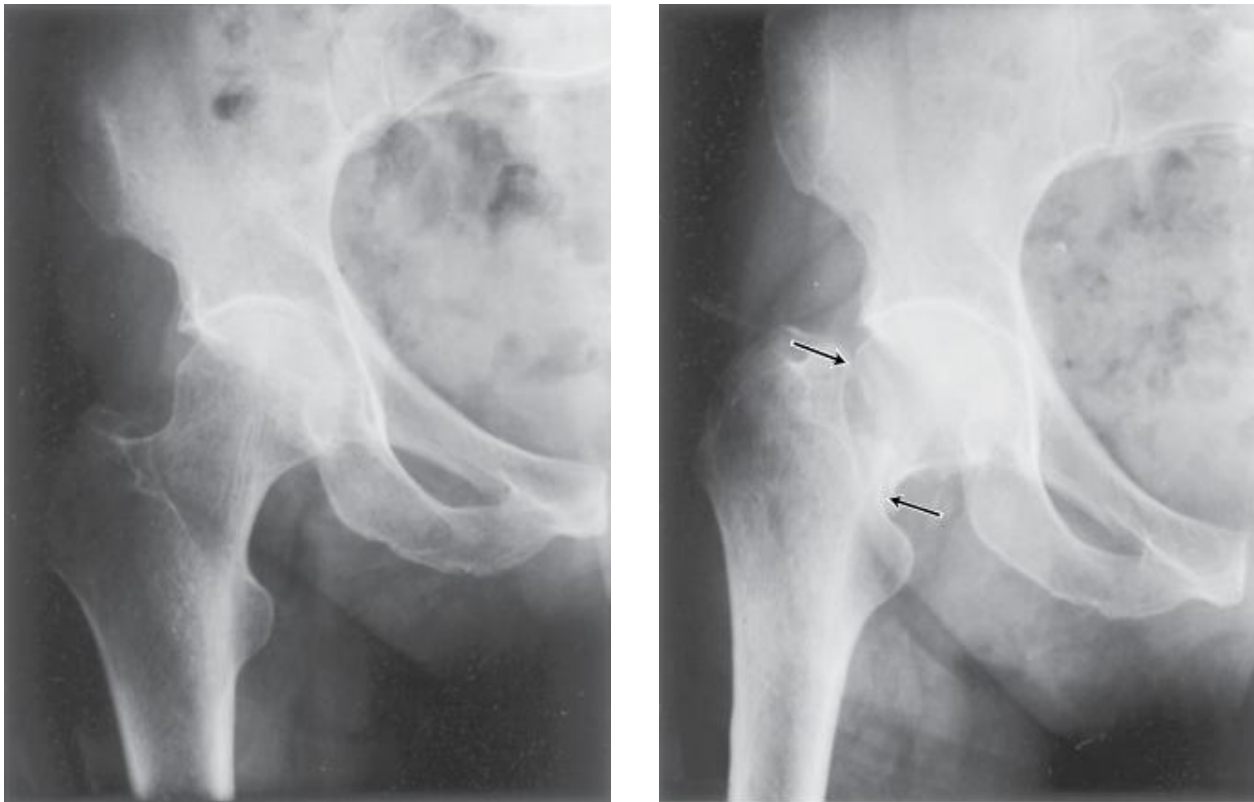
- What is materials science?
- Why should we know about it?

- Materials drive our society
 - Stone Age
 - Bronze Age
 - Iron Age
 - Now?
 - Silicon Age?
 - Polymer Age?



Example – Hip Implant

- With age or certain illnesses joints deteriorate. Particularly those with large loads (such as hip).

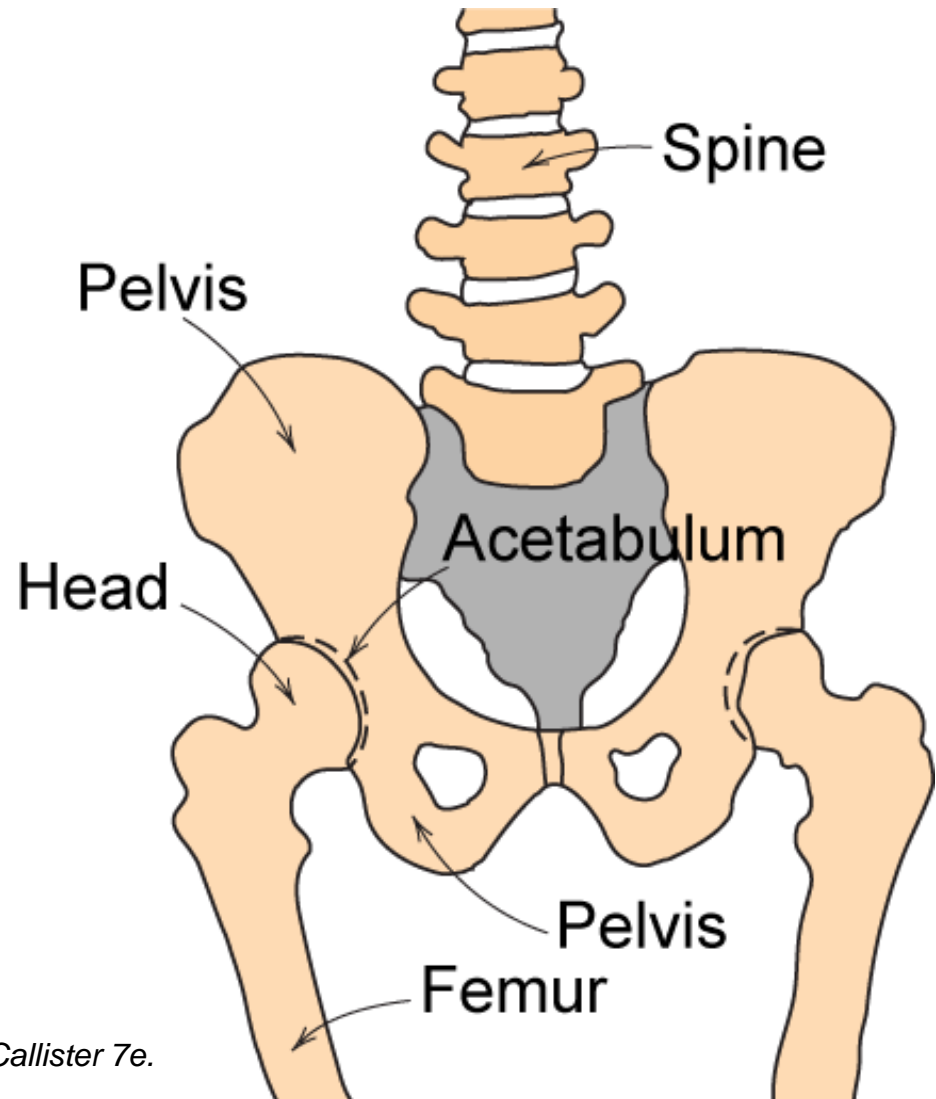


Adapted from Fig. 22.25, *Callister 7e*.



Example – Hip Implant

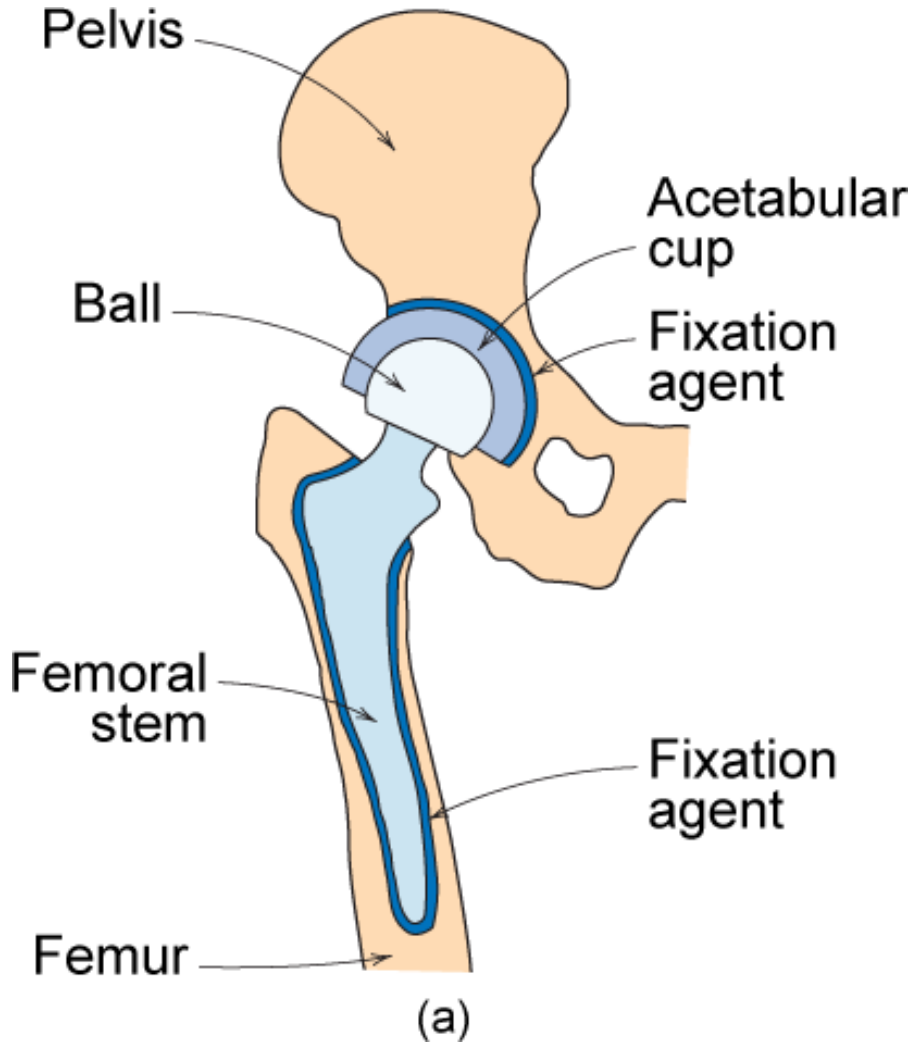
- Requirements
 - mechanical strength (many cycles)
 - good lubricity
 - biocompatibility



Adapted from Fig. 22.24, *Callister 7e*.



Example – Hip Implant



(b)

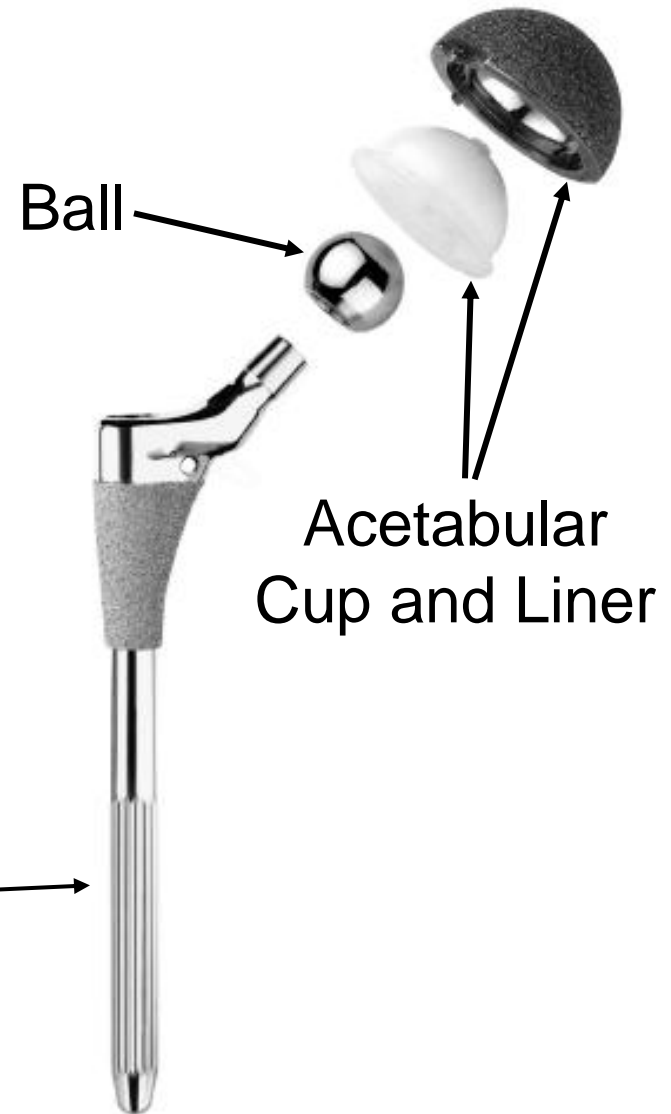
Adapted from Fig. 22.26, *Callister 7e*.



Hip Implant

- Key problems to overcome
 - fixation agent to hold acetabular cup
 - cup lubrication material
 - femoral stem – fixing agent (“glue”)
 - must avoid any debris in cup

Femoral
Stem



Adapted from chapter-opening photograph,
Chapter 22, *Callister 7e*.

Example – Develop New Types of Polymers

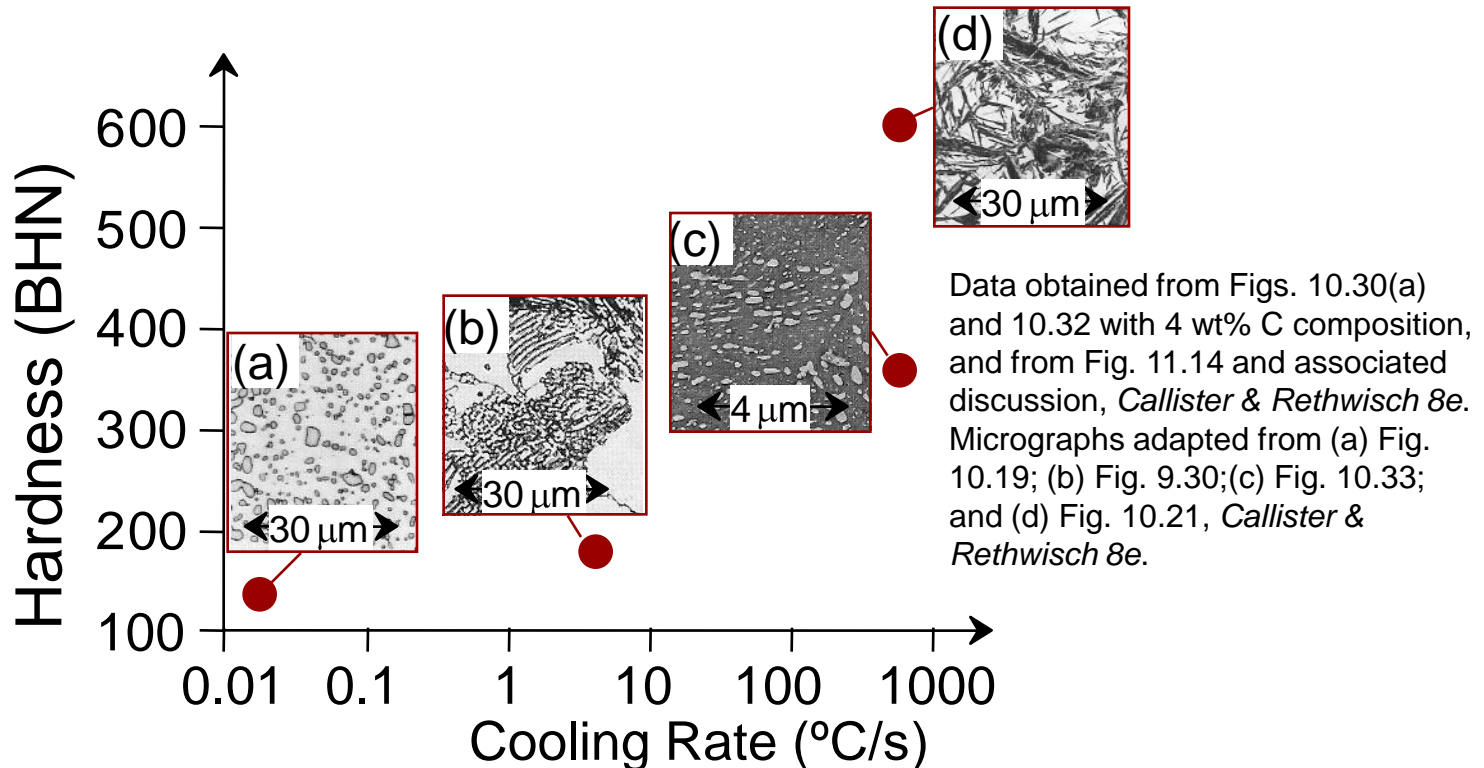
- **Commodity plastics** – large volume ca. \$0.50 / lb
 - Ex. Polyethylene
 - Polypropylene
 - Polystyrene
 - etc.
- **Engineering Resins** – small volume > \$1.00 / lb
 - Ex. Polycarbonate
 - Nylon
 - Polysulfone
 - etc.

Can polypropylene be “upgraded” to properties (and price) near those of engineering resins?



Structure, Processing, & Properties

- **Properties** depend on **structure**
ex: hardness vs structure of steel



- **Processing** can change **structure**
ex: structure vs cooling rate of steel



Types of Materials

- **Metals:**
 - Strong, ductile
 - High thermal & electrical conductivity
 - Opaque, reflective.
- **Polymers/plastics:** Covalent bonding → sharing of e's
 - Soft, ductile, low strength, low density
 - Thermal & electrical insulators
 - Optically translucent or transparent.
- **Ceramics:** ionic bonding (refractory) – compounds of metallic & non-metallic elements (oxides, carbides, nitrides, sulfides)
 - Brittle, glassy, elastic
 - Non-conducting (insulators)



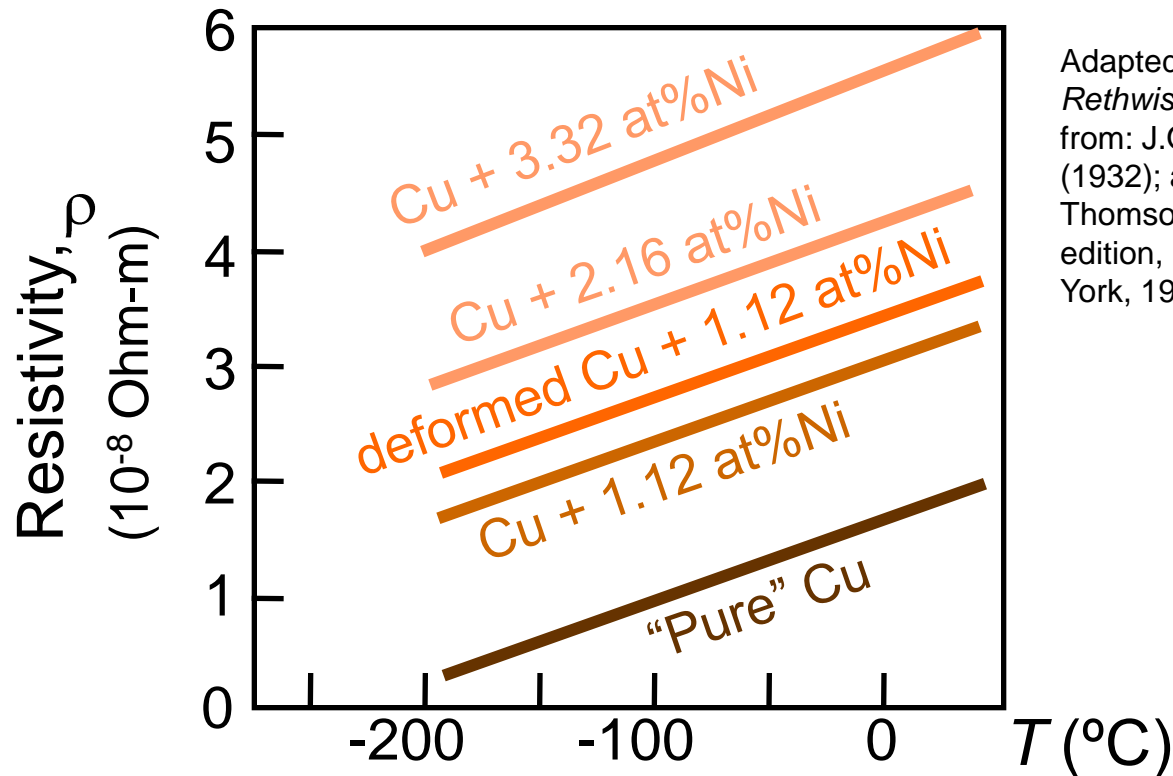
The Materials Selection Process

1. Pick **Application** → Determine required **Properties**
Properties: mechanical, electrical, thermal, magnetic, optical, deteriorative.
2. **Properties** → Identify candidate **Material(s)**
Material: structure, composition.
3. **Material** → Identify required **Processing**
Processing: changes *structure* and overall *shape*
ex: casting, sintering, vapor deposition, doping
forming, joining, annealing.



ELECTRICAL

- Electrical Resistivity of Copper:



Adapted from Fig. 18.8, *Callister & Rethwisch 8e*. (Fig. 18.8 adapted from: J.O. Linde, *Ann Physik* **5**, 219 (1932); and C.A. Wert and R.M. Thomson, *Physics of Solids*, 2nd edition, McGraw-Hill Company, New York, 1970.)

- Adding “impurity” atoms to Cu increases resistivity.
- Deforming Cu increases resistivity.

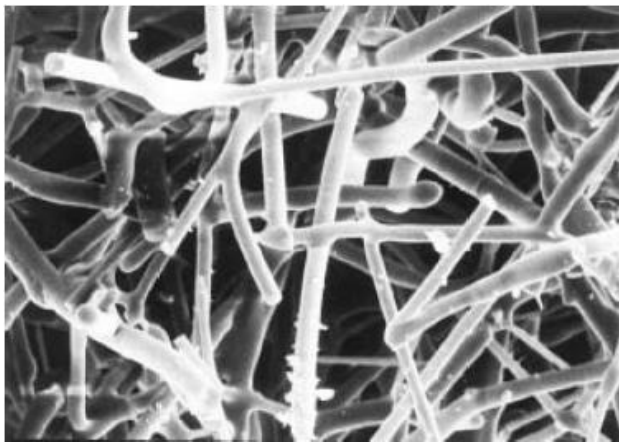


THERMAL

- Space Shuttle Tiles:
 - Silica fiber insulation offers low **heat conduction**.



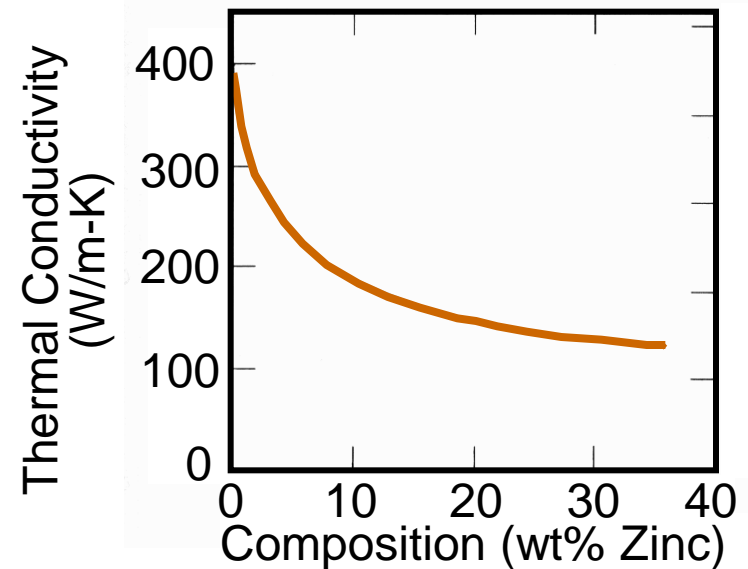
Adapted from chapter-opening photograph, Chapter 17, *Callister & Rethwisch 3e*. (Courtesy of Lockheed Missiles and Space Company, Inc.)



← 100 μm →

Adapted from Fig. 19.4W, *Callister 6e*. (Courtesy of Lockheed Aerospace Ceramics Systems, Sunnyvale, CA) (Note: "W" denotes fig. is on CD-ROM.)

- **Thermal Conductivity of Copper:**
 - It decreases when you add zinc!



Adapted from Fig. 19.4, *Callister & Rethwisch 8e*. (Fig. 19.4 is adapted from *Metals Handbook: Properties and Selection: Nonferrous alloys and Pure Metals*, Vol. 2, 9th ed., H. Baker, (Managing Editor), American Society for Metals, 1979, p. 315.)



MAGNETIC

- **Magnetic Storage:**
 - Recording medium is magnetized by recording head.

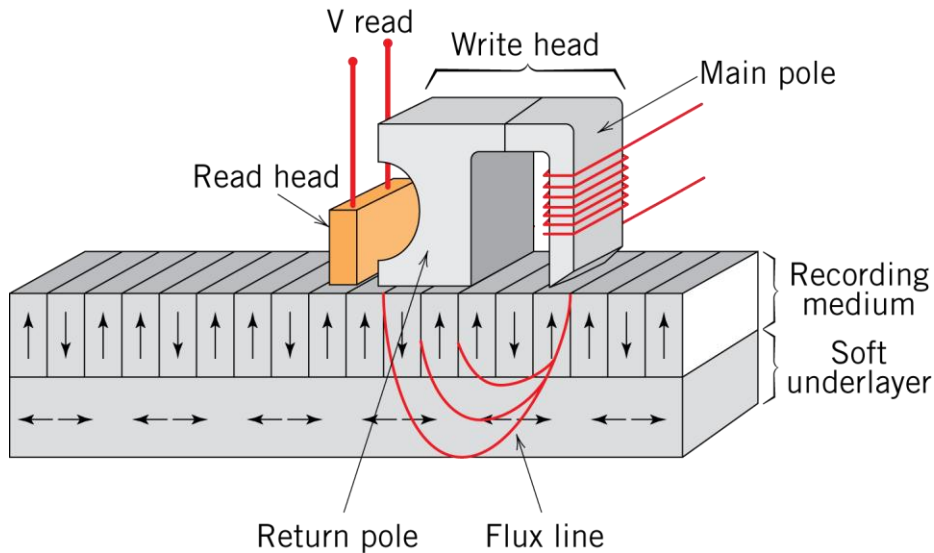
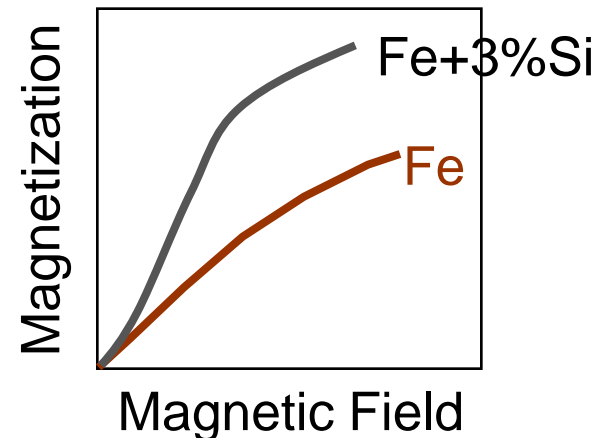


Fig. 20.23, Callister & Rethwisch 8e.

- **Magnetic Permeability vs. Composition:**
 - Adding 3 atomic % Si makes Fe a better recording medium!

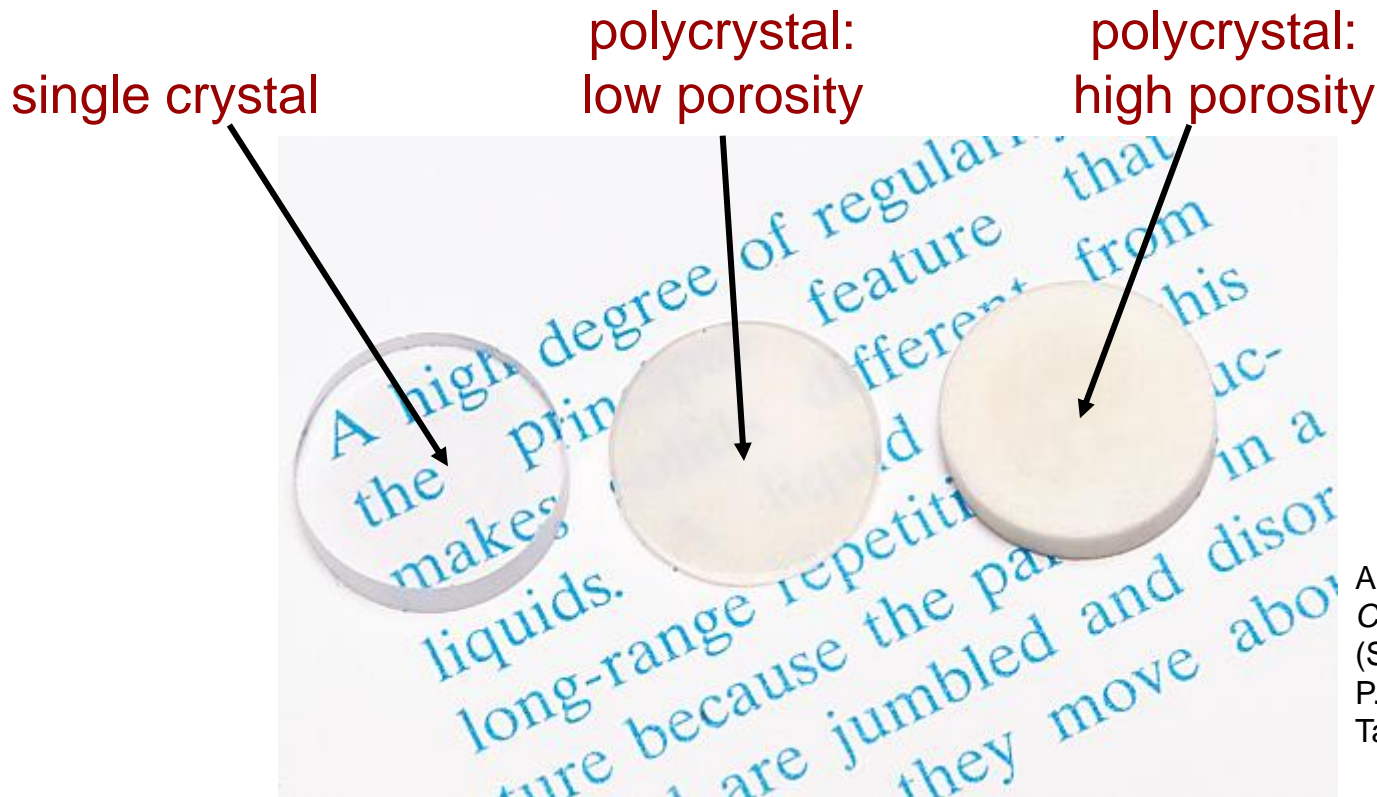


Adapted from C.R. Barrett, W.D. Nix, and A.S. Tetelman, *The Principles of Engineering Materials*, Fig. 1-7(a), p. 9, 1973. Electronically reproduced by permission of Pearson Education, Inc., Upper Saddle River, New Jersey.



OPTICAL

- **Transmittance:**
 - Aluminum oxide may be transparent, translucent, or opaque depending on the material structure.

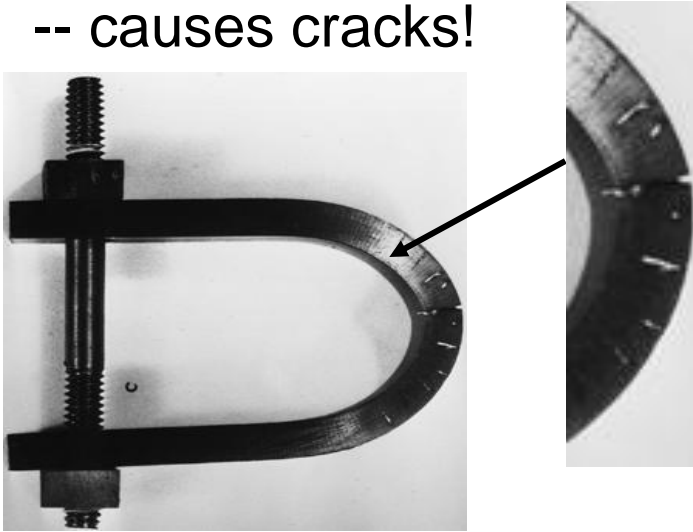


Adapted from Fig. 1.2,
Callister & Rethwisch 8e.
(Specimen preparation,
P.A. Lessing; photo by S.
Tanner.)



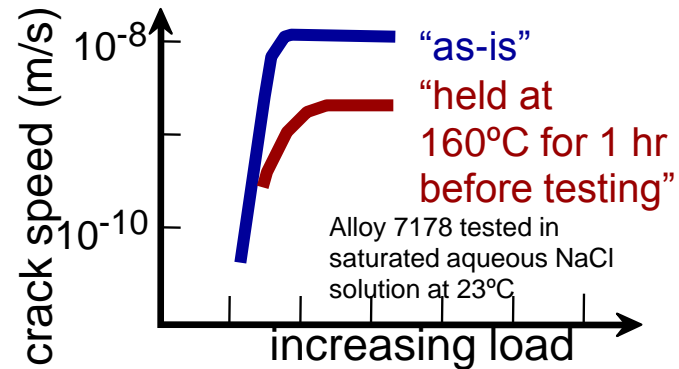
DETERIORATIVE

- Stress & Saltwater...
-- causes cracks!



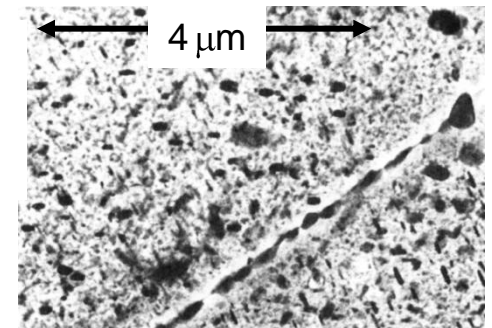
Adapted from chapter-opening photograph, Chapter 16, *Callister & Rethwisch 3e*. (from *Marine Corrosion, Causes, and Prevention*, John Wiley and Sons, Inc., 1975.)

- Heat treatment: slows crack speed in salt water!



Adapted from Fig. 11.20(b), R.W. Hertzberg, "Deformation and Fracture Mechanics of Engineering Materials" (4th ed.), p. 505, John Wiley and Sons, 1996. (Original source: Markus O. Speidel, Brown Boveri Co.)

- material:
7150-T651 Al "alloy"
(Zn,Cu,Mg,Zr)



Adapted from Fig. 11.26, *Callister & Rethwisch 8e*. (Provided courtesy of G.H. Narayanan and A.G. Miller, Boeing Commercial Airplane Company.)



SUMMARY

Course Goals:

- Use the right material for the job.
- Understand the relation between **properties**, **structure**, and **processing**.
- Recognize new design opportunities offered by materials selection.

